



Title	Formation of titanium oxide thin film on biomedical magnesium alloy by high dose titanium and oxygen dual ion implantation
Author(s)	Zhao, Y; Wu, GS; Chu, PK; Yeung, KWK
Citation	The 2011 International Thin Films Conference of Taiwan Association for Coatings and Thin Films Technology (TACT 2011), Pingtung, Taiwan, 20-23 November 2011.
Issued Date	2011
URL	http://hdl.handle.net/10722/160375
Rights	Creative Commons: Attribution 3.0 Hong Kong License

Formation of Titanium Oxide Thin Film on Biomedical Magnesium Alloy by High Dose Titanium and Oxygen Dual Ion Implantation

Ying Zhao (趙穎)^{1, 2†}, Guosong Wu (吳國松)², Paul K Chu (朱劍豪)^{2‡},
Kelvin W. K. Yeung (楊偉國)^{1‡}

¹Department of Orthopaedics & Traumatology, The University of Hong Kong
(香港大學矯形及創傷科學矯系)

²Department of Physics and Materials Science, City University of Hong Kong
(香港城市大學物理與材料系)

(Acknowledgement: This work was jointly supported by HKU Seed Funding for Basic Research as well as RGC GRFs #123708 and #112501)

WE43 magnesium alloy is potentially biodegradable metallic stent material due to its good mechanical property and corrosion resistance. However, the fast degradation rate in the physiological environment cannot meet clinical needs. In order to further enhance the corrosion resistance, high dose titanium and oxygen ion implantation is performed to modify the surface of the WE43 magnesium alloy in this study. X-ray photoelectron spectroscopy (XPS) is used to characterize the microstructures in the near surface layer, whereas electrochemical impedance spectroscopy, potentiodynamic polarization, and immersion test are employed to investigate the corrosion resistance of the implanted alloys in simulated body fluids (SBF). The results indicate that titanium and oxygen dual ion implantation produces a titanium oxide thin film which significantly enhances the corrosion resistance of WE43 alloy. Our data suggest a simple and practical means to improve the corrosion resistance of magnesium implants.

† Presenter: Ying Zhao

‡ Corresponding author: Kelvin W. K. Yeung, E-mail: wkkyeung@hku.hk,
Paul K. Chu, Email: paul.chu@cityu.edu.hk